

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	3.0	A
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

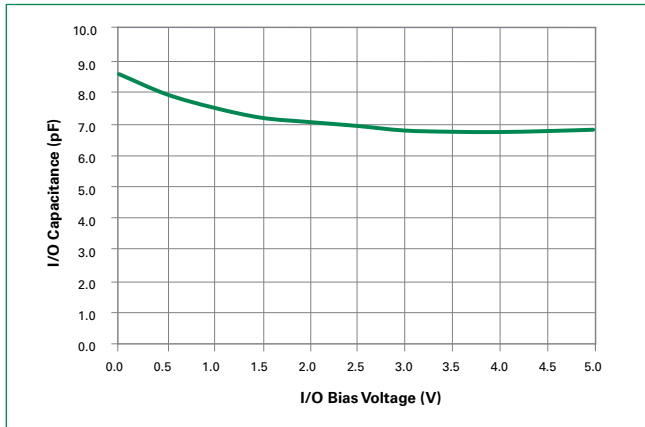
### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$				6.0	V
Breakdown Voltage	$V_{BR}$	$I_R=1mA$		7.0	8.5	V
Leakage Current	$I_{LEAK}$	$V_R=5V$ with 1 pin at GND		0.1		$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		10.7		V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		12.0		V
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.3		W
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact Discharge)	$\pm 15$			kV
		IEC 61000-4-2 (Air Discharge)	$\pm 15$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=5.0V		6	9	pF

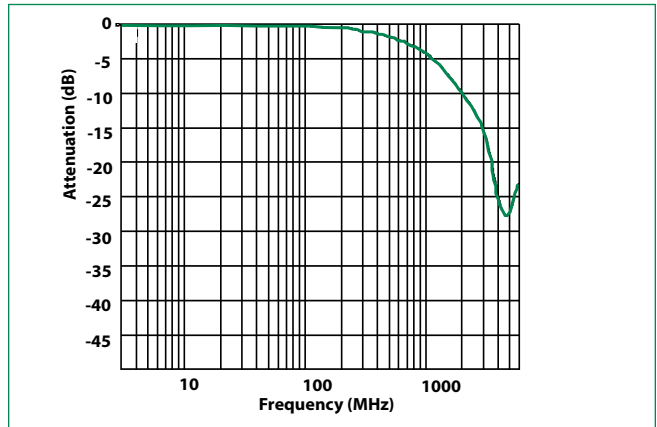
**Note:**

<sup>1</sup>Parameter is guaranteed by design and/or device characterization.

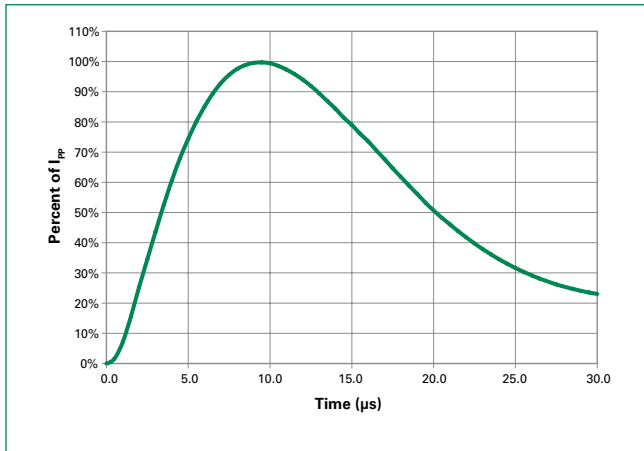
### Capacitance vs. Reverse Bias



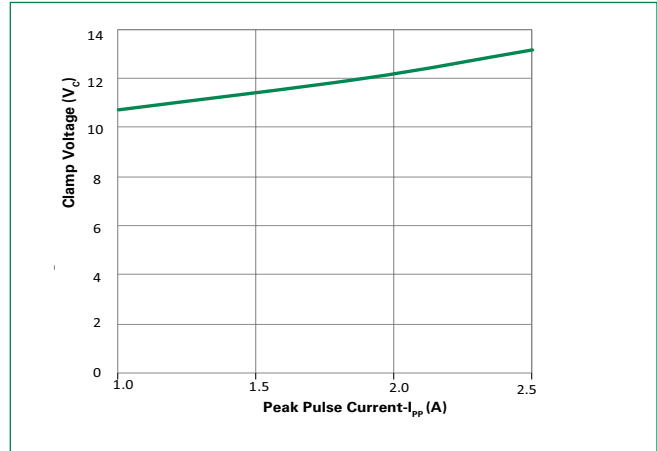
### Insertion Loss (S21) I/O to GND



**Pulse Waveform**

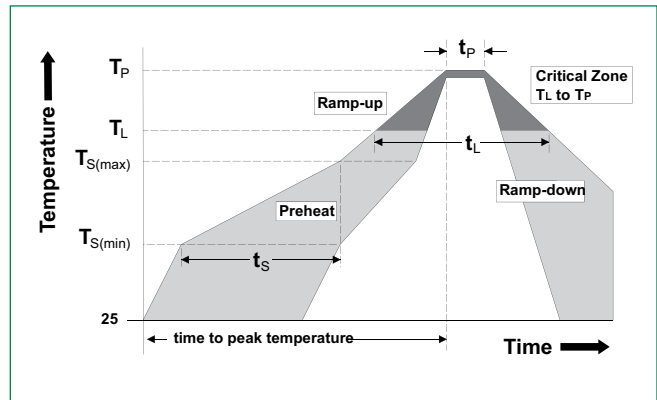


**Clamping Voltage vs.  $I_{PP}$**

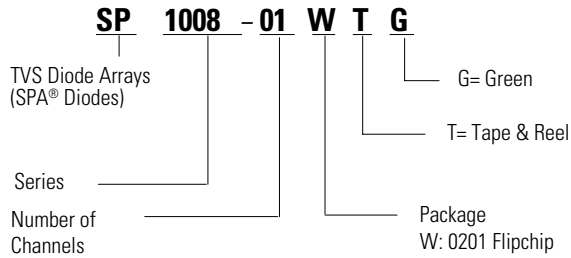


**Soldering Parameters**

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_p$ )	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		260°C



**Part Numbering System**



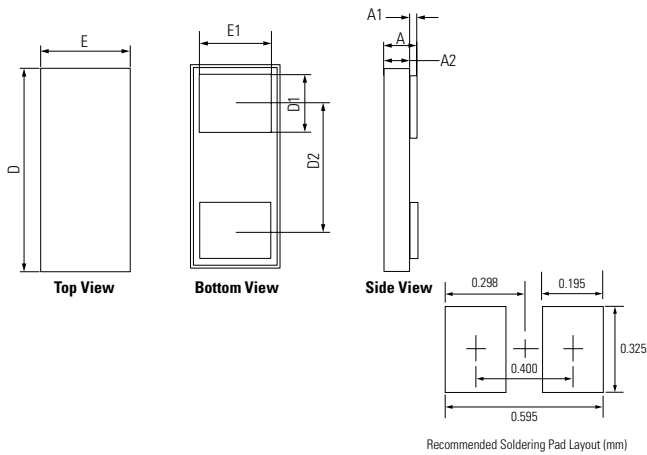
**Ordering Information**

Part Number	Package	Min. Order Qty.
SP1008-01WTG	0201 Flipchip	10000

**Part Marking System**

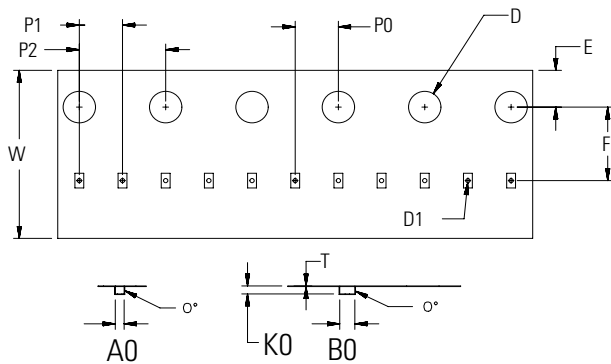


**Package Dimensions — 0201 Flipchip**



Symbol	0201 Flipchip			
	Millimeters		Inches	
	Min	Max	Min	Max
D	0.605	0.655	0.0238	0.0258
E	0.305	0.345	0.0120	0.0140
D1	0.145	0.155	0.0057	0.0061
E1	0.245	0.255	0.0096	0.0100
D2	0.400 BSC		0.0157 BSC	
A	0.273	0.329	0.0107	0.0130
A2	0.265	0.315	0.0104	0.0124
A1	0.008	0.014	0.0003	0.0006

**Embossed Carrier Tape & Reel Specification — 0201 Flipchip**



Symbol	Millimeters
A0	0.41±0.03
B0	0.70±0.03
D	∅ 1.50 + 0.10
D1	∅ 0.20 ± 0.05
E	1.75±0.10
F	3.50±0.05
K0	0.38±0.03
P0	2.00±0.05
P1	2.00±0.05
P2	4.00±0.10
W	8.00 + 0.30 -0.10
T	0.23±0.02

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